TOSHIBA TLP822,TLP827

TOSHIBA PHOTO-INTERRUPTERS INFRARED LED + PHOTOTRANSISTOR

# TLP822, TLP827

VCRS, COMPACT DISC PLAYERS
FLOPPY DISK DRIVES, FAX MACHINES, PRINTERS
VENDING MACHINES, TICKET MACHINES
VARIOUS POSITION DETECTION SENSORS

The TLP822 and TLP827 photo-interrupters combine a high-radiant-power GaAs infrared LED with an Si phototransistor.

Small package

• Side mounting type : TLP822

Designed for direct mounting on printed circuit boards

: TLP827

(the oblong slit)

• Gap : 5 mm

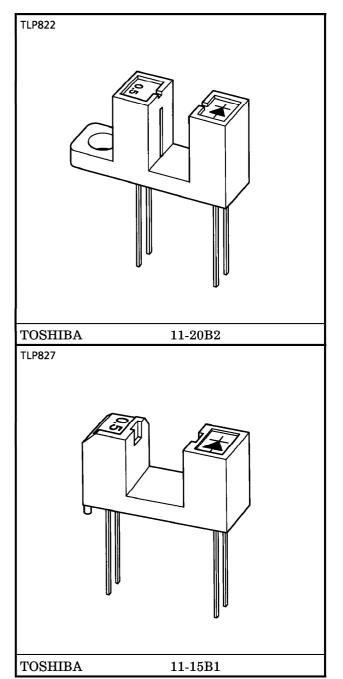
• Resolution : Slit width = 0.5 mm

• High current transfer ratio :  $I_C/I_F = 5\%$  (min)

at  $I_F = 10 \text{ mA}$ 

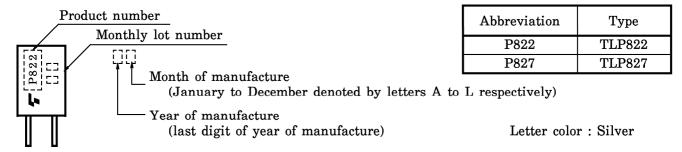
Detector impermeable to visible light

Package material : Polycarbonate



Weight: 0.87 g (typ.) 0.72 g (typ.)

## **MARKINGS**



## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC			SYMBOL	RATING	UNIT	
	Forward Current		${ m I_F}$	50	mA	
ED	Forward Current	(Ta>25°C)	4T /0G	-0.33	mA/°C	
ΓI	Derating	(Ta>85°C)	$\Delta I_{\mathbf{F}} / {^{\circ}\mathbf{C}}$	-2 (Note)		
	Reverse Voltage		$v_{R}$	5	V	
R	Collector-Emitter Voltage		$v_{CEO}$	35	V	
TO	Emitter-Collector Voltage		$v_{ECO}$	5	V	
EC	Collector Power Dissipation		PC	75	mW	
ΕT	Collector Power Dissipation Derating		△P <sub>C</sub> / °C	-1	mW/°C	
DI	Collector Current		$I_{\mathbb{C}}$	50	mA	
Op	erating	$ m T_{opr}$	-25~85	°C		
Te	Temperature Range TLP827		-25~95			
St	orage Temperature	$T_{ m stg}$	-40~100	°C		
Soldering Temperature (5 s)			$T_{sol}$	260	°C	

(Note): TLP827 only

#### RECOMMENDED OPERATING CONDITIONS

CHARACTERISTIC	SYMBOL	Min	Тур.	Max	UNIT
Supply Voltage	$v_{CC}$	_	5	24	V
Forward Current	$I_{\mathbf{F}}$	_	10	20	mA
Operating Temperature	$T_{ m opr}$	-10	ı	75	°C

## OPTICAL AND ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	CHARACTERISTIC	SYMBOL	TEST CONDITION	Min	Тур.	Max	UNIT
LED	Forward Voltage	$ m V_{ m F}$	$I_{ m F}=10{ m mA}$		1.15	1.30	V
	Reverse Current	$I_{\mathbf{R}}$	$V_R = 5 V$	_	_	10	$\mu$ A
	Peak Emission Wavelength	$\lambda_{\mathbf{P}}$	$I_{ m F}=10{ m mA}$		940		nm
DETECTOR	Dark Current	ID (ICEO)	$V_{ m CE} = 24 \  m V, \ I_{ m F} = 0$	1		0.1	$\mu$ A
DETE	Peak Sensitivity Wavelength	$\lambda_{\mathbf{P}}$	_	1	870	-	nm
ΓΑ	Current Transfer Ratio	$I_{\mathbf{C}}/I_{\mathbf{F}}$	$ m V_{CE} = 2~V,~I_{F} = 10~mA$	5	_	75	%
COUPLED	Collector-Emitter Saturation Voltage	V <sub>CE</sub> (sat)	$ m I_F = 20~mA,~I_C = 0.5~mA$		0.1	0.4	V
	Rise Time	$t_{\mathbf{r}}$	$V_{CC} = 5 \text{ V}, I_{C} = 1 \text{ mA},$	_	15	50	
Ľ	Fall Time	$t_f$	$R_{\rm L} = 1  { m k} \Omega$	_	15	50	$\mu$ s

#### **PRECAUTIONS**

The following points must be borne in mind.

1. Clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent.

2. The package is made of polycarbonate. Polycarbonate is usually stable with acid, alcohol and aliphatic hydrocarbons; however, with petrochemicals (such as benzene, toluene and acetone), alkalis, aromatic hydrocarbons, or chloric hydrocarbons, polycarbonate may crack, swell or melt. Please take this into account when chosing a packaging material by referring to the table below.

<Chemicals which should not be used with polycarbonate>

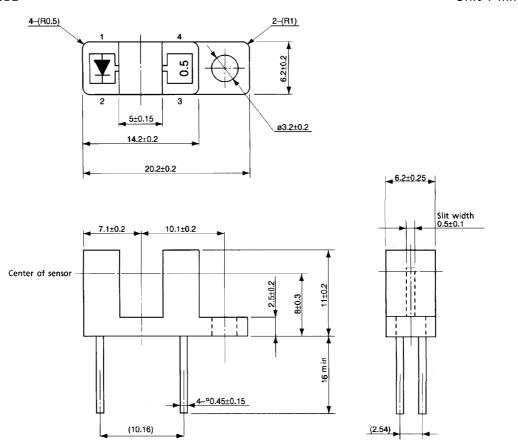
	PHENOMENON	CHEMICALS	
A	Staining and slight deterioration	• Nitric acid (diluted), hydrogen peroxide, chlorine	
В	Cracking, crazed or swelling	<ul> <li>Acetic acid (70% or more)</li> <li>Gasoline</li> <li>Methyl ethyl ketone, ethyl acetate, butyl acetate</li> <li>Ethyl methacrylate, ethyl ether, MEK</li> <li>Acetone, m-amino alcohol, carbon tetrachloride</li> <li>Carbon disulfide, trichloroethylene, cresol</li> <li>Thinners, oil of turpentine</li> <li>Triethanolamine, TCP, TBP</li> </ul>	
C	Melting { }: Used as solvent	<ul> <li>Concentrated sulfuric acid</li> <li>Benzene</li> <li>Styrene, acrylonitrile, vinyl acetate</li> <li>Ethylenediamine, diethylenediamine</li> <li>Chloroform, methyl chloride, tetrachloromethane, dioxane,</li> <li>1, 2-dichloroethane</li> </ul>	
D	Decomposition	Ammonia water     Other alkalis	

- 3. Mount the device on a level surface.
- 4. Screws should be tightened to a clamping torque of 0.59 N·m.
- 5. Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

$$\frac{I_{C}/I_{F}(t)}{I_{C}/I_{F}(0)} = \frac{P_{O}(t)}{P_{O}(0)}$$

## PACKAGE DIMENSIONS 11-20B2

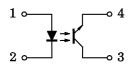
Unit: mm



(): Reference value

Weight: 0.87 g (typ.)

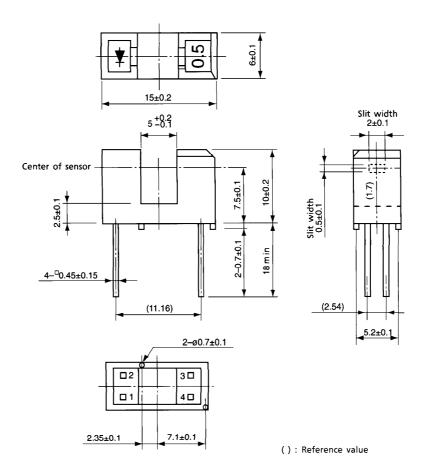
## PIN CONNECTION



- 1. ANODE
- 2. CATHODE
- 3. COLLECTOR
- 4. EMITTER

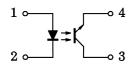
## PACKAGE DIMENSIONS 11-15B1

Unit: mm

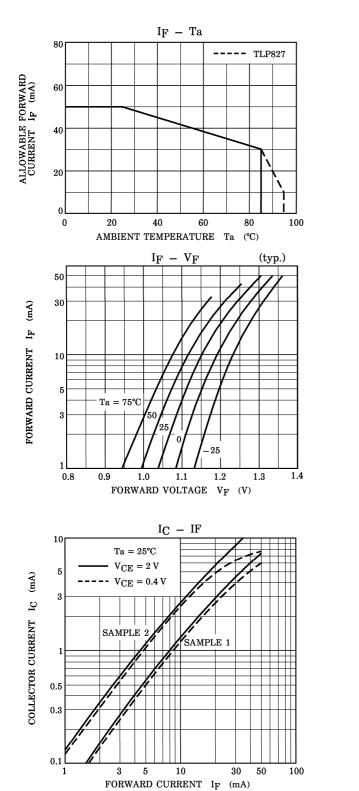


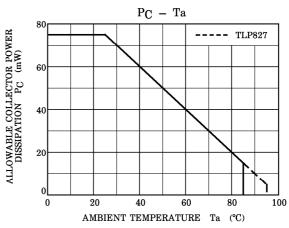
Weight: 0.72 g (typ.)

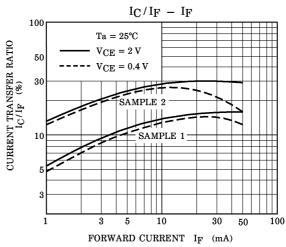
## PIN CONNECTION

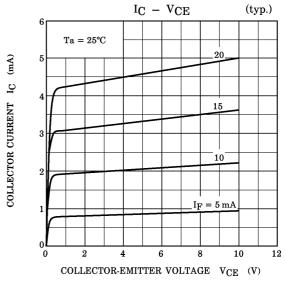


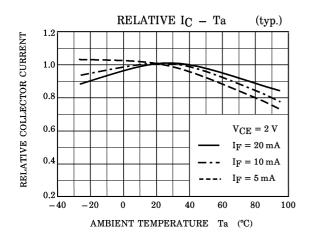
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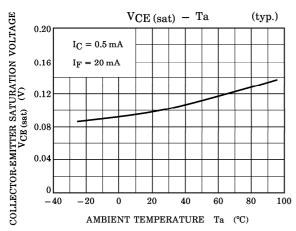


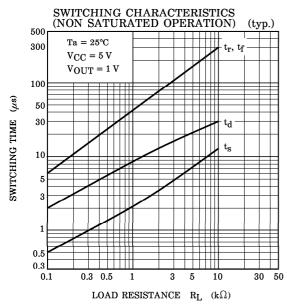


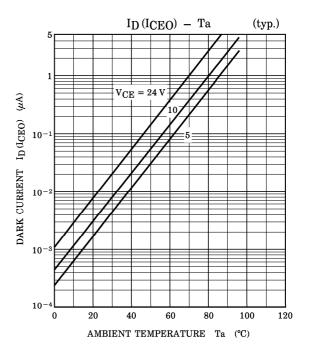




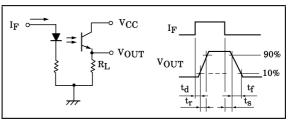


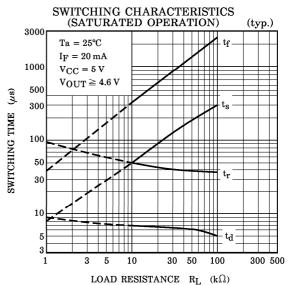


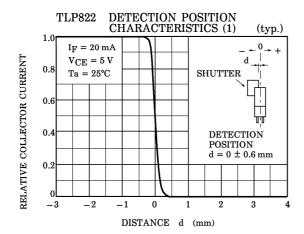


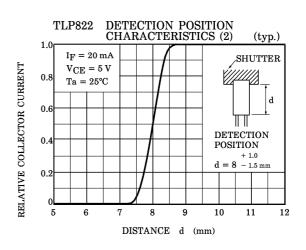


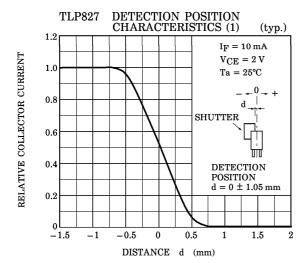
#### SWITCHING TIME TEST CIRCUIT

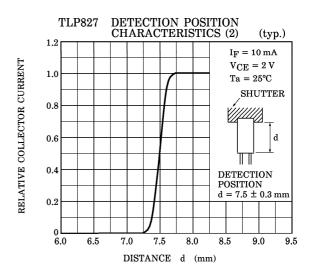








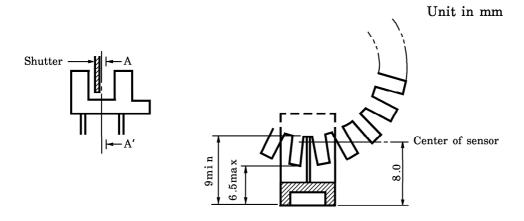




## RELATIVE POSITIONING OF SHUTTER AND DEVICE

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection position characteristic and switching time, determine the shutter slit width and pitch.

#### **TLP822**



Cross section between A and A'

#### RESTRICTIONS ON PRODUCT USE

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